

## Congeners in DIN Method PCBs

**Column:** DB-XLB  
30 m x 0.25 mm I.D., 0.5 µm  
1 m x 0.53 mm I.D. Retention Gap

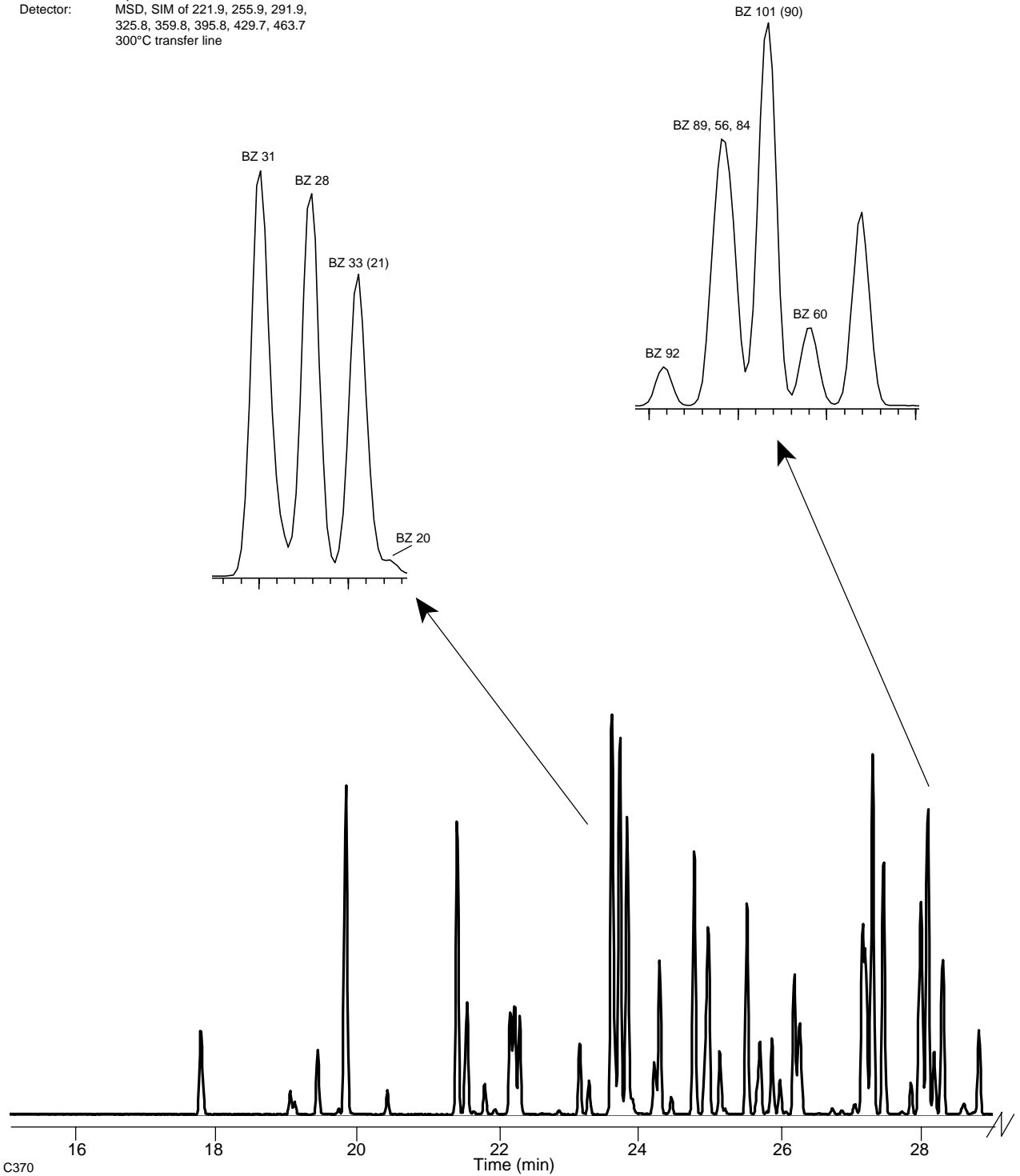
**J&W P/N:** 122-1236

**Carrier:** Helium at 34.2 cm/sec, measured at 150°C

**Oven:** 100°C for 1 min  
100-320°C at 5.6°/min

**Injector:** Hot On-column, 250°C, Split Flow  
100 mL/min  
2 µL dilute Aroclor mixture

**Detector:** MSD, SIM of 221.9, 255.9, 291.9,  
325.8, 359.8, 395.8, 429.7, 463.7  
300°C transfer line



# PCBs Continued

## Extended Temperature Program Resolving Congeners 52 and 138

**Column:** DB-XLB  
30 m x 0.25 mm I.D., 0.5 µm  
1 m x 0.53 mm I.D. Retention Gap

**J&W P/N:** 122-1236

**Carrier:** Helium at 34.2 cm/sec, measured at 150°C

**Oven:** 100°C for 1 min  
100-275°C at 1.6°/min

**Injector:** Hot On-column, 250°C, Split Flow  
100 mL/min

**Detector:** MSD, SIM of 221.9, 255.9, 291.9, 325.8,  
359.8, 395.8, 429.7, 463.7  
300°C transfer line

